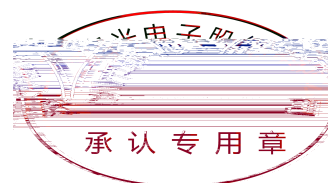


# SPECIFICATION

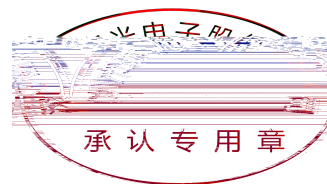
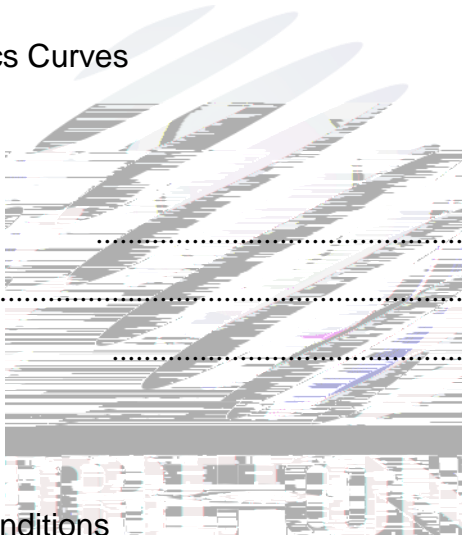


Mass Production



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4.1 Handling Precautions	



## 1. Description

### 1.1

The source color devices are made with AlGaInp on Substrate Light Emitting Diode .  
Product Package:3.50mmX2.80mmX1.84mm.

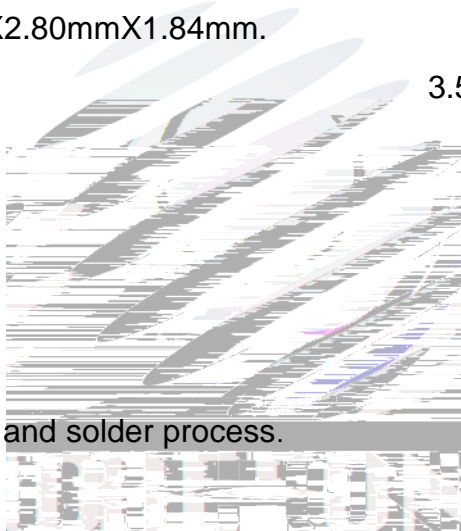
3.50mmX2.80mmX1.84mm.

### 1.2 Features

PLCC2 Package.

Extremely wide viewing angle.

Suitable for all SMT assembly and solder process.



## 1.4 Package Dimension

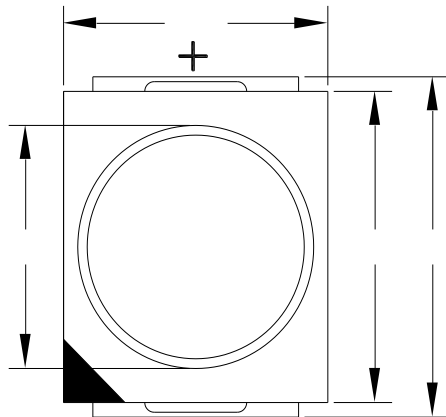


Fig.1-1 Top View

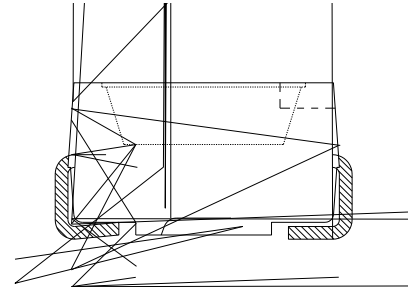


Fig.1-2 Side View

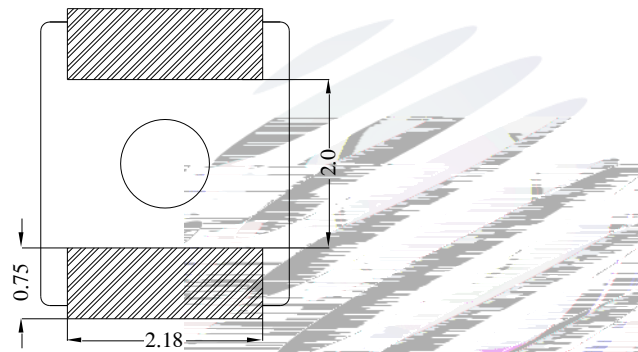


Fig.1-3 Bottom View

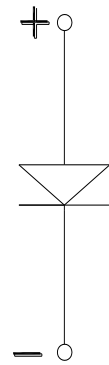


Fig.1-4 Polarity

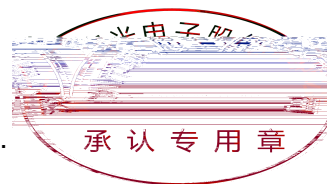


Fig.1-5 Soldering Patterns

### Notes

All dimensions units are millimeters.

All dimensions tolerances are  $\pm 0.2\text{mm}$  unless otherwise noted.



±

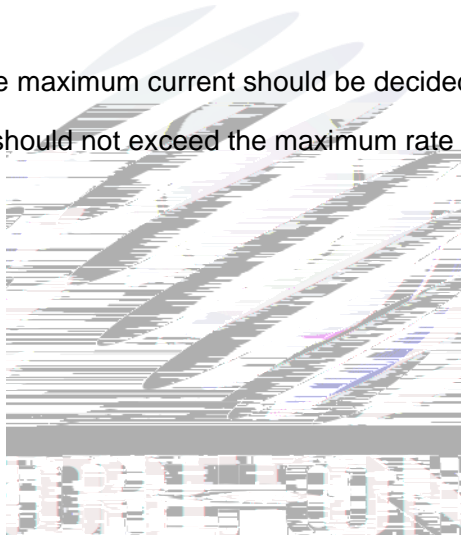
## 1.5 Product Parameters



Notes

1. 1/10 Duty cycle, 10ms pulse width.
2. The above forward voltage measurement allowance tolerance is  $\pm 0.1V$ .  $\pm 0.1V$ .
3. The above color coordinates measurement allowance tolerance is  $\pm 0.005$ .  $\pm$
4. The above luminous intensity measurement allowance tolerance  $\pm 10\%$ .  $\pm 10\%$ .
5. Care is to be taken that power dissipation does not exceed the absolute maximum rating of the product.
6. All measurements were made under the standardized environment of Refond.
7. When the LEDs are in operation the maximum current should be decided after measuring the package temperature, junction temperature should not exceed the maximum rate

8. ESD yield is over 90% at 2



## 1.7 Typical Optical Characteristics Curves

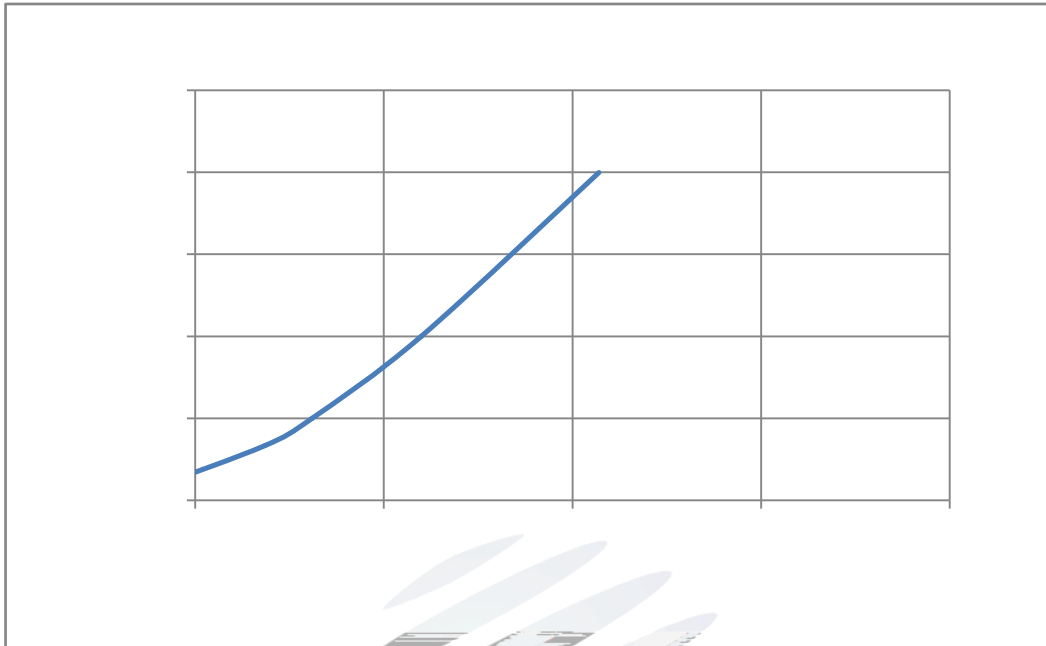


Fig. 1-7 Forward Voltage Vs Forward Current

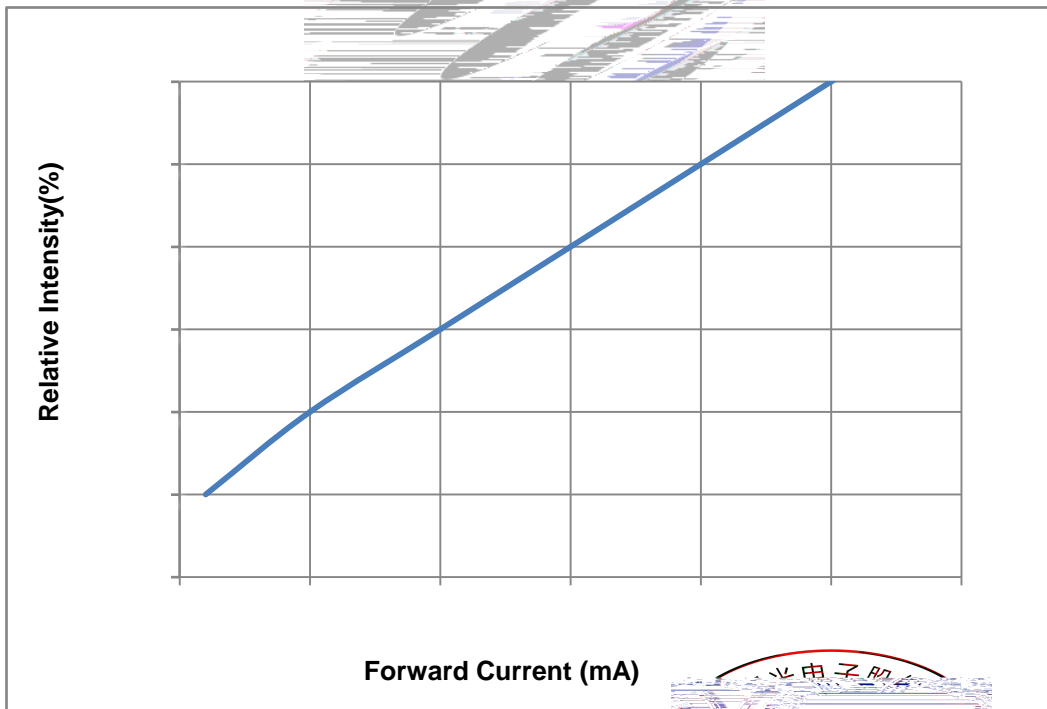


Fig. 1-8 Forward Current Vs Relative Intensity

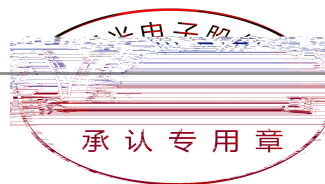


Fig. 1-9 Solder Temperature Vs Relative Intensity

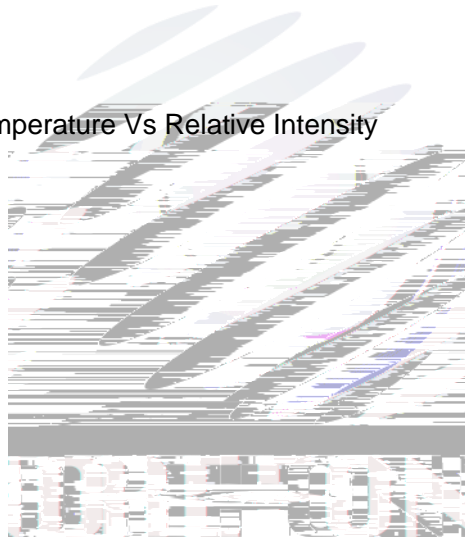


Fig. 1-10 Solder Temperature Vs Forward Current



Fig. 1-11 Forward Voltage Vs Solder Temperature

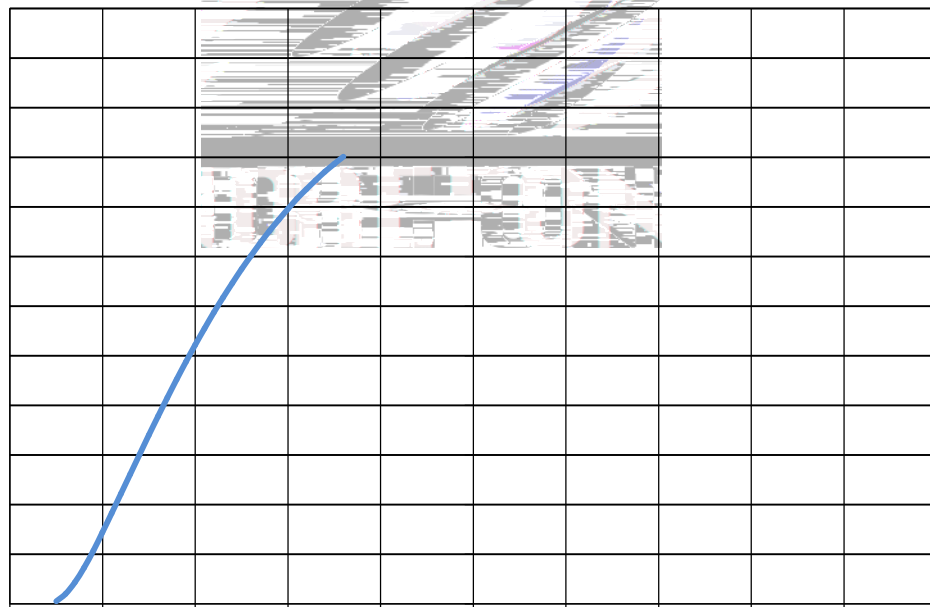


Fig. 1-12 Radiation diagram

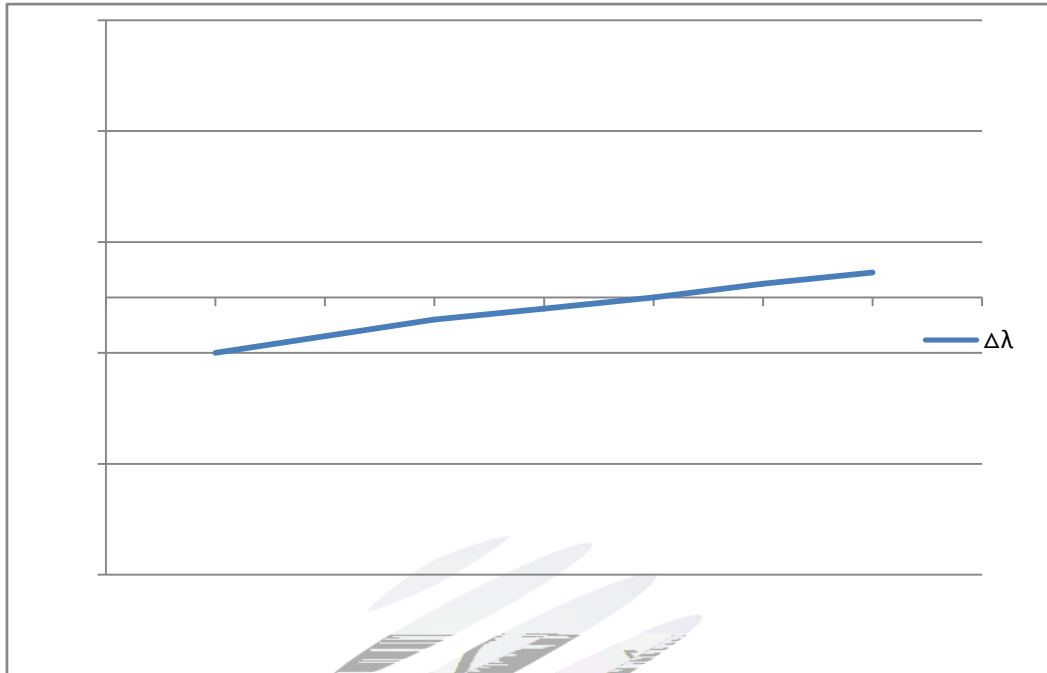


Fig. 1-13 Forward current vs. Dominate wavelength (Ts=25°C)

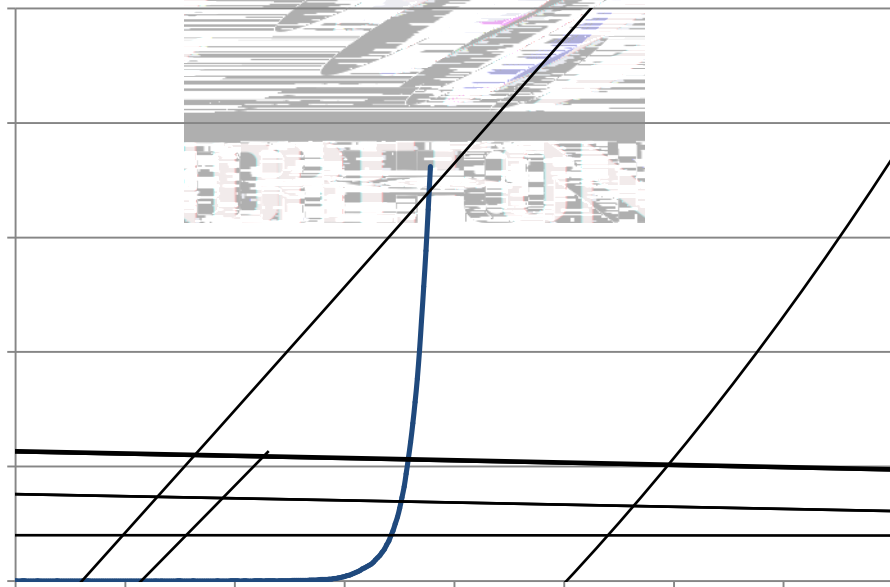
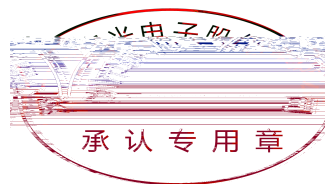


Fig. 1-14 Spectrum Distribution



## 2. Packaging

### 2.1 Packaging Specification

Package:2000pcs/reel.

#### 2.1.1 Carrier Tape Dimension

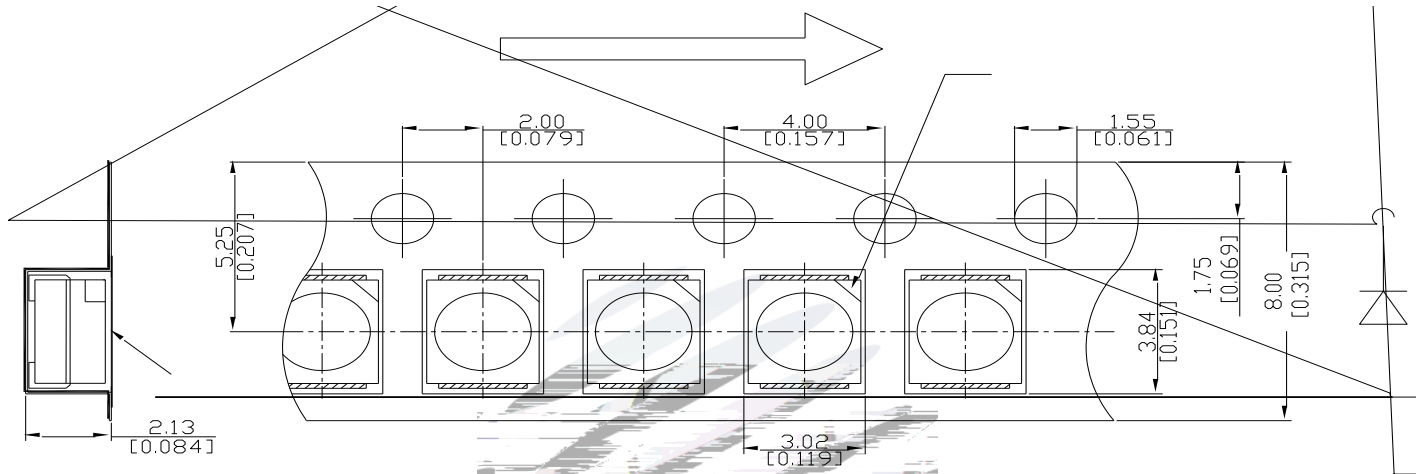


Fig.2-1 Carrier Tape Dimension

#### 2.1.2 Reel Dimension

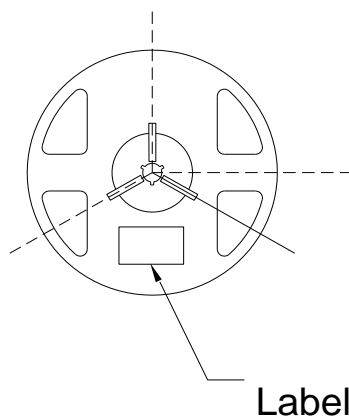


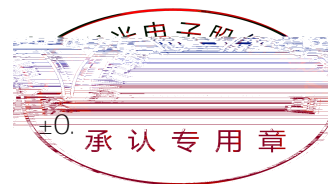
Fig.2-2 Reel Dimension

Reel Dimension

A	8.0±0.1mm
B	178±1mm
C	60±1mm
D	13.0±0.5mm

#### Notes

The tolerances unless mentioned ±0.1mm. Unit : mm



### 2.1.3 Label Form Specification

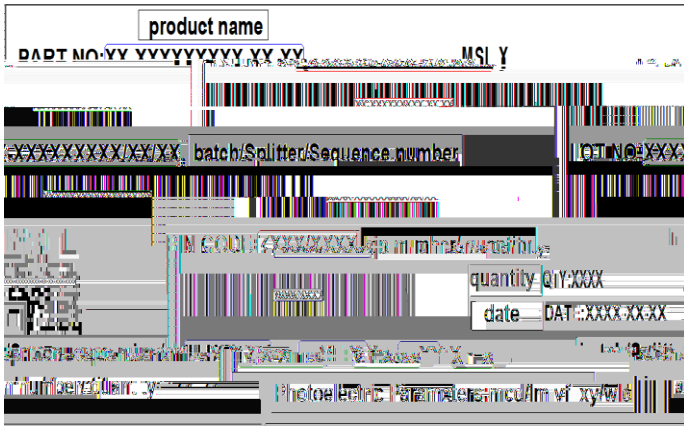


Fig. 2-3 Label Form Specification

#### Specification

PART NO.	Part Number
SPEC NO.	Spec Number
LOT NO.	Lot Number
BIN CODE	Bin Code
	Luminous flux
XY	Chromaticity Bin
V <sub>F</sub>	Forward Voltage
WLD	Wavelength
QTY	Packing Quantity
DATE	Made Date

### 2.2 Moisture Resistant Packing

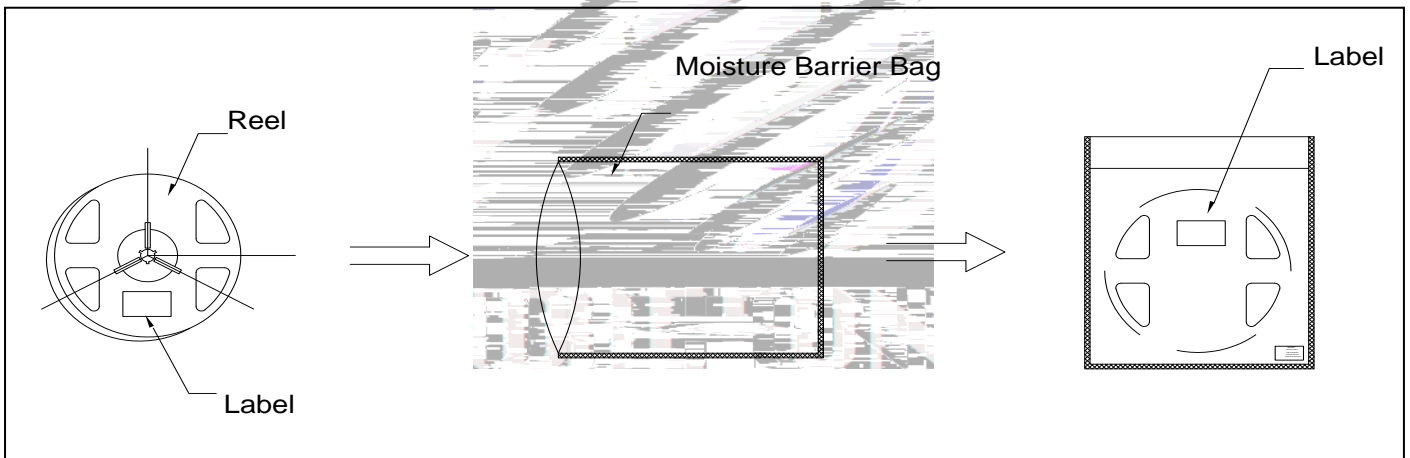
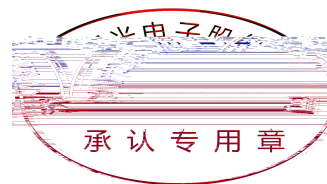


Fig.2-4 Moisture Resistant Packing



## 2.3 Cardboard Box

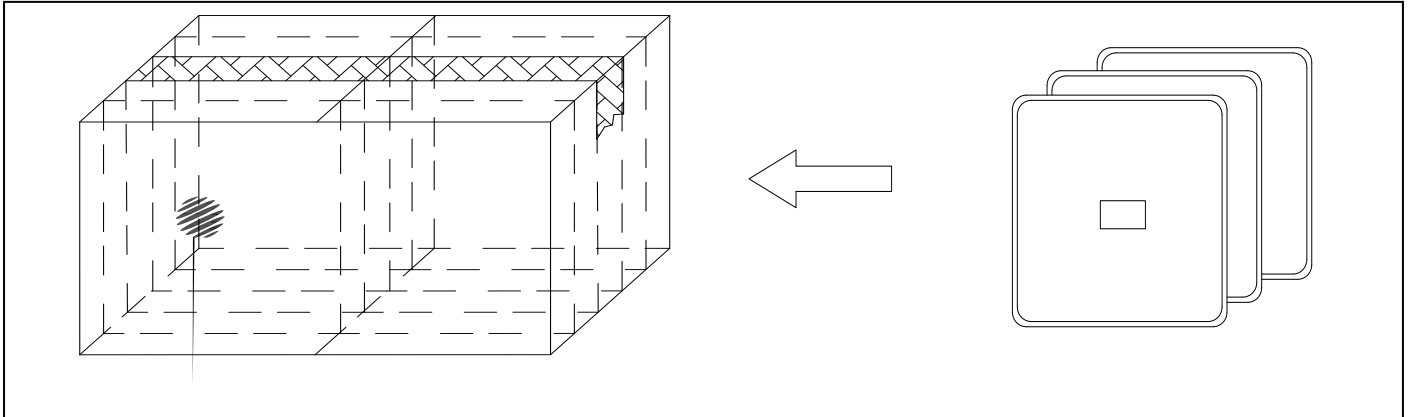
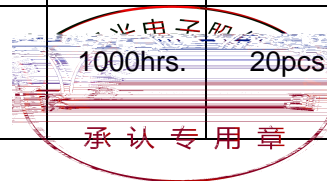


Fig.2- Cardboard Box

## 2.4 Reliability Test Items And Conditions

Table 2-3 Reliability Test Items And Conditions

Test Items	Ref.Standard	Test Condition	Time	Quantity	Ac/Re /
Reflow	JEESD22-B106	Temp:260 max T=10 sec	2times	20pcs.	0/1
Thermal Shock	JEITAED-4701 300307	-40 15min 10s 125 15min	1000 cycle	20pcs.	0/1
High Temperature Storage	JEITAED-4701 200 201	Temp:125	1000hrs.	20pcs.	0/1
Low Temperature Storage	JEITA ED-4701 200 202	Temp:-40	1000hrs.	20pcs.	0/1
Life Test	JESD22-A108	Ta=25 If=20mA	1000hrs.	20pcs.	0/1



High Temperature High Humidity Life Test	JESD22-A101	85 / 85%RH I <sub>F</sub> =20mA	1000hrs.	20pcs.	0/1
Temperature Humidity Storage	JEITA ED-4701 100 103	T <sub>A</sub> =85 R <sub>H</sub> =85%	1000hrs.	20pcs.	0/1

## 2.5 Criteria For Judging Damage

Table 2-4 Criteria For Judging Damage

Test Items	Symbol	Test Condition	Criteria For Judgement	
			Min.	Max.
Forward Voltage	V <sub>F</sub>	I <sub>F</sub> =20mA	-	U.S.L*)x1.1
Reverse Current	I <sub>R</sub>	V <sub>R</sub> = 5V	-	U.S.L*)x2.0
Luminous Flux		I <sub>F</sub> =20mA	L.S.L*)x0.7	-

### Notes

- 1.U.S.L: Upper standard level                      L.S.L: Lower standard level
- 2.The above reliability tests is based on the verification of a single/strip LED of Refond's existing experimental platform,the reliability experiment



Time limit classification of peak temperature time $t_p$	10	Max 10s
( $T_p$ ) 5 °C with the actual peak temperature (TP) Hold time within 5 °C	30	Max 30s
Cooling speed	6 °C/	Max 6 °C/ s
25 °C Needed time from 25 °C to $T_p$	8	Max 8 minutes

#### Notes

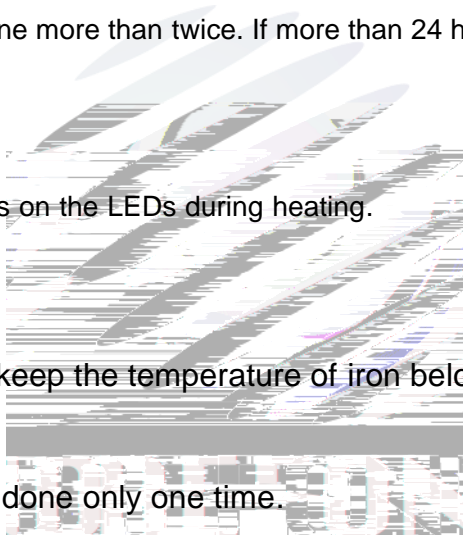
(1) Reflow soldering should not be done more than twice. If more than 24 hours between the two solderings, LED will be damaged.

(2) When soldering, do not put stress on the LEDs during heating.

#### 3.1.1 Soldering Iron

(1) When do soldering by hand, keep the temperature of iron below less 300 less than 3 seconds

(2) Soldering by hand should be done only one time.

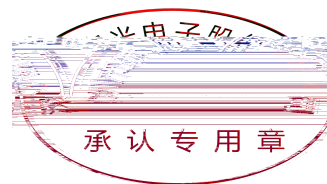


#### 3.1.2 Repairing

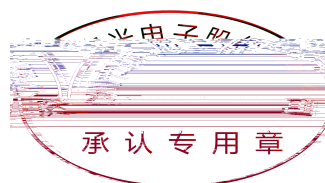
Repairing should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed in advance whether the characteristics of LEDs will or not be damaged by repairing.

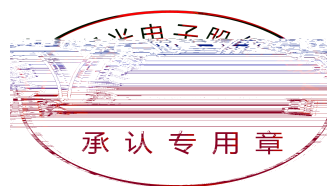
LED

#### 3.1.3 Cautions









(6) Thermal Design is paramount importance because heat generation may result in the Characteristics decline, such as brightness decreased, Color change and so on. Please consider the heat generation of the LEDs when making the system design. LED

(7) Compared to standard encapsulants, silicone is generally softer, and the surface is more likely to attract dust, requiring special care during processing. In cases where a minimal level of dirt and dust particles cannot be guaranteed, a suitable cleaning solution must be applied to the surface after the soldering of components. Refond suggests using isopropyl alcohol for cleaning. In case other solvents are used, it must be assured that these solvents do not dissolve the package or resin. Ultrasonic cleaning is not recommended. Ultrasonic cleaning may cause damage to the LED.

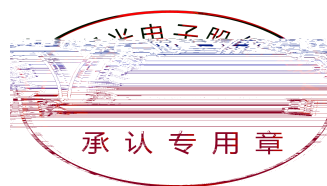


Table 4-1 Storage

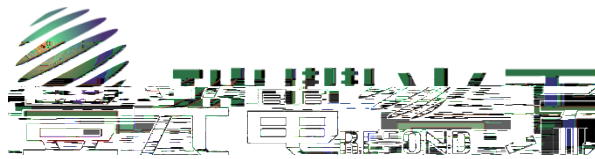
Conditions		Temperature	Humidity	Time
Storage	Before Opening Aluminum Bag	30	75%	Within 1 Year From Date
	After Opening Aluminum Bag	30	60%	Recommended for use within 24 hours

Baking

60±5







www.refond.com



Declare

This specification is written both in English and in Chinese and the latter is formal.

